

EAST SEARCH PR 10/27/05

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L41	3	(porous adj adhesive adj sheet).clm.	US-PGPUB	OR	ON	2005/10/27 11:22
L42	502	(adhesive adj sheet).clm.	US-PGPUB	OR	ON	2005/10/27 11:23
L43	116	((adhesive adj sheet) and (hole or void or opening)).clm.	US-PGPUB	OR	ON	2005/10/27 11:23

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3451	adhesive with conductive with film	USPAT	OR	ON	2005/10/27 09:13
L2	1295	anisotropic adj conductive adj film	USPAT	OR	ON	2005/10/27 09:35
L3	0	2 same oligomer	USPAT	OR	ON	2005/10/27 09:13
L4	25	2 and oligomer	USPAT	OR	ON	2005/10/27 09:21
L5	19	"6121553"	USPAT	OR	ON	2005/10/27 09:24
L6	30	thermoset\$4 adj oligomer	USPAT	OR	ON	2005/10/27 09:24
L7	801	2 and adhesive	USPAT	OR	ON	2005/10/27 09:32
L8	734	7 and (metal\$3 or insulating)	USPAT	OR	ON	2005/10/27 09:32
L9	296	7 and (through adj hole)	USPAT	OR	ON	2005/10/27 09:32
L11	1754	anisotropic and conductive and adhesive	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:35
L12	733	anisotropic and conductive and adhesive and (metal or insulat\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:35
L13	29	12 and (through adj hole)	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:38
L14	117	12 and (softening or glass or melt\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:38
L15	111	14 not 13	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:38
L24	2640	428/304.4	USPAT	OR	ON	2005/10/27 10:30
L25	690	428/317.1	USPAT	OR	ON	2005/10/27 10:31
L26	305	428/317.5	USPAT	OR	ON	2005/10/27 10:31
L27	458	428/317.3	USPAT	OR	ON	2005/10/27 10:31
L28	3386	428/343	USPAT	OR	ON	2005/10/27 10:31
L29	6761	24 or 25 or 26 or 27 or 28	USPAT	OR	ON	2005/10/27 10:31
L30	96	29 and (wire with (etch\$3 or remov\$3))	USPAT	OR	ON	2005/10/27 10:37
L31	121	29 and (adhesive near5 hole)	USPAT	OR	ON	2005/10/27 10:37
L32	117	31 not 30	USPAT	OR	ON	2005/10/27 10:37
S1	32714	adhesive and hole	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:11
S2	4919	S1 and (wire or fiber or fibre)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:11
S3	242	S2 and (wash\$3 or etch\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:12
S4	2704	S1 and (wafer or semiconductor)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:12
S5	68	S3 and S4	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:17

S6	22284	(wire or fiber or fibre) with (etch\$3 or wash\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:17
S7	151	S6 and adhesive near5 (layer or sheet)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:18
S8	146	S7 not S5	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:28
S9	7969	adhesive and (through adj hole)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:28
S10	1360	S9 and (wafer or semiconductor or solder)	EPO; JPO; DERWENT	OR	ON	2005/10/24 15:28
S11	721	S10 and (adhesive with hole)	EPO; JPO; DERWENT	OR	ON	2005/10/24 16:00
S12	2930	adhesive with (through adj hole)	USPAT	OR	ON	2005/10/25 09:40
S13	597	S12 and (wire same adhesive)	USPAT	OR	ON	2005/10/25 09:40
S14	310	S13 and (semiconductor or wafer)	USPAT	OR	ON	2005/10/25 10:06
S15	3719	adhesive same (hole or opening) same (etch\$3 or wash\$3)	USPAT	OR	ON	2005/10/25 10:06
S16	368	S15 same (wire or fiber or fibre)	USPAT	OR	ON	2005/10/25 10:07
S17	270	S16 and (electrical or wafer or semiconductor)	USPAT	OR	ON	2005/10/25 10:07
S18	251	S17 not S14	USPAT	OR	ON	2005/10/25 10:45
S19	7969	adhesive and (through adj hole)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:45
S20	503	S19 and (etch\$3 or wash\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:45
S21	85581	adhesive adj (sheet or layer)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:45
S22	4465	S21 and (hole)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:45
S23	369	S22 and (etch\$3 or wash\$3)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:46
S24	129	S20 and S23	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:53
S25	6082	etch\$3 with wire	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:53
S26	11259	wash\$3 with (fiber or fibre)	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:54
S27	17340	S25 or S26	EPO; JPO; DERWENT	OR	ON	2005/10/25 10:54
S28	66	S27 and (adhesive adj (sheet or layer))	EPO; JPO; DERWENT	OR	ON	2005/10/25 11:01
S29	16268	holes with (adhesive)	EPO; JPO; DERWENT	OR	ON	2005/10/25 11:02
S30	2299	holes with (adhesive adj (sheet or layer))	EPO; JPO; DERWENT	OR	ON	2005/10/25 11:03

S31	732	(through adj holes) with (adhesive adj (sheet or layer))	EPO; JPO; DERWENT	OR	ON	2005/10/25 11:03
S32	151	S31 and (etch\$3 or wash\$3 or remov\$4)	EPO; JPO; DERWENT	OR	ON	2005/10/25 12:02
S33	1975	holes with (adhesive adj (sheet or layer))	USPAT	OR	ON	2005/10/25 12:02
S34	2734	etch\$3 near5:wire	USPAT	OR	ON	2005/10/25 12:02
S35	184	S34 and (adhesive same (hole or opening))	USPAT	OR	ON	2005/10/25 12:43
S36	1800	156/290	USPAT	OR	ON	2005/10/25 12:44
S37	376	S36 and (semiconductor or wafer or electrical)	USPAT	OR	ON	2005/10/25 12:44
S38	386	S36 and (adhesive same (hole or open\$4))	USPAT	OR	ON	2005/10/25 12:44
S39	90	S37 and S38	USPAT	OR	ON	2005/10/25 12:48
S40	541	216/17	USPAT	OR	ON	2005/10/25 12:52
S41	721	216/18	USPAT	OR	ON	2005/10/25 12:52
S42	1100	S40 or S41	USPAT	OR	ON	2005/10/25 12:52
S43	152	S42 and (adhesive same (hole or aperature or opening))	USPAT	OR	ON	2005/10/25 13:01
S44	1556	adhesive and (remov\$3 near5 (wir\$3 or fibre or fiber))	EPO; JPO; DERWENT	OR	ON	2005/10/25 13:01
S45	161	adhesive and (remov\$3 near5 (wir\$3 or fibre or fiber)) and (semiconductor or wafer or electrical)	EPO; JPO; DERWENT	OR	ON	2005/10/25 13:31
S46	72	adhesive and (etch\$3 near5 wire)	EPO; JPO; DERWENT	OR	ON	2005/10/25 13:31
S47	70	S46 not S45	EPO; JPO; DERWENT	OR	ON	2005/10/25 14:06
S48	1013	hole near5 (adhesive adj (sheet or layer))	EPO; JPO; DERWENT	OR	ON	2005/10/25 14:06
S49	325	(through adj hole) near5 (adhesive adj (sheet or layer))	EPO; JPO; DERWENT	OR	ON	2005/10/25 14:37
S50	4525	coat\$3 with (through adj hole)	EPO; JPO; DERWENT	OR	ON	2005/10/25 14:37
S51	779	S50 and (semiconductor or wafer or electrical)	EPO; JPO; DERWENT	OR	ON	2005/10/25 14:37
S52	771	S51 not S49	EPO; JPO; DERWENT	OR	ON	2005/10/25 16:05
S53	9	"6245175"	USPAT	OR	ON	2005/10/26 08:32
S54	8	"560072"	EPO; JPO; DERWENT	OR	ON	2005/10/26 09:16
S55	1	"6245175"	EPO; JPO; DERWENT	OR	ON	2005/10/26 09:50

S56	1	1998-159800.NRAN.	DERWENT	OR	ON	2005/10/26 09:16
S57	1	1998-159800.NRAN.	DERWENT	OR	ON	2005/10/26 09:48
S58	103	semiconductor and wafer and through and hole and solder	EPO; JPO; DERWENT	OR	ON	2005/10/26 09:51
S59	43	S58 and electrode	EPO; JPO; DERWENT	OR	ON	2005/10/26 09:52
S60	5	US-4666751-\$.DID. OR US-4404243-\$.DID. OR US-4346700-\$.DID. OR US-5604026-\$.DID. OR US-5435480-\$.DID.	USPAT	OR	ON	2005/10/26 14:34
S61	1	oligomer and adhesive and (through adj hole)	EPO; JPO; DERWENT	OR	ON	2005/10/26 14:34
S62	122	oligomer and adhesive and semiconductor	EPO; JPO; DERWENT	OR	ON	2005/10/26 14:49
S63	31	(through adj hole) and (oligomer with adhesive)	USPAT	OR	ON	2005/10/26 14:59
S64	33	semiconductor same oligomer same adhesive	USPAT	OR	ON	2005/10/26 14:59
S65	32	S64 not S63	USPAT	OR	ON	2005/10/26 14:59
S66	57	adhesive and conductive and oligomer	EPO; JPO; DERWENT	OR	ON	2005/10/27 09:13